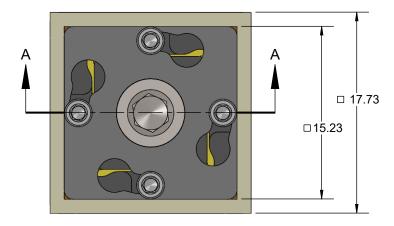
GHz QFNSocket - Direct mount, solderless

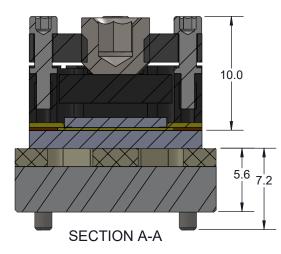
Features

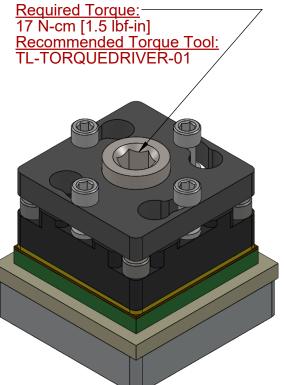
- Directly mounts to target PCB (needs tooling holes) with hardware
 High speed, reliable Elastomer connection

- Minimum real estate required
 Compression plate distributes forces evenly
 Easily removable swivel socket lid



TOP VIEW





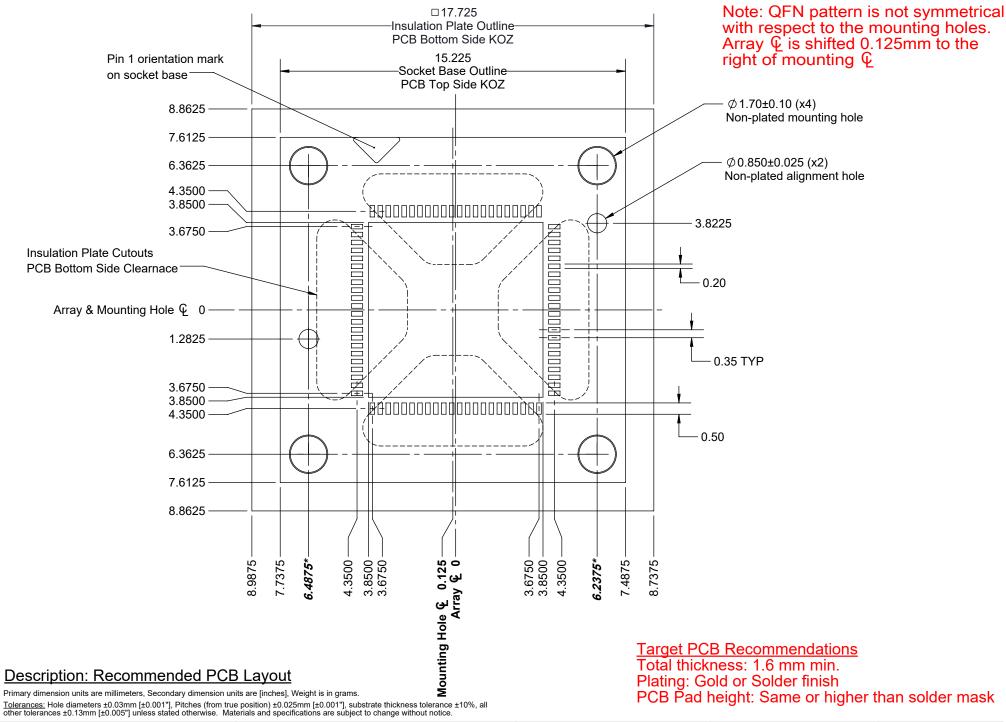
ISO VIEW

Description: SG25-QFN88, 9x9mm, 0.35mm pitch, Swivel Lid

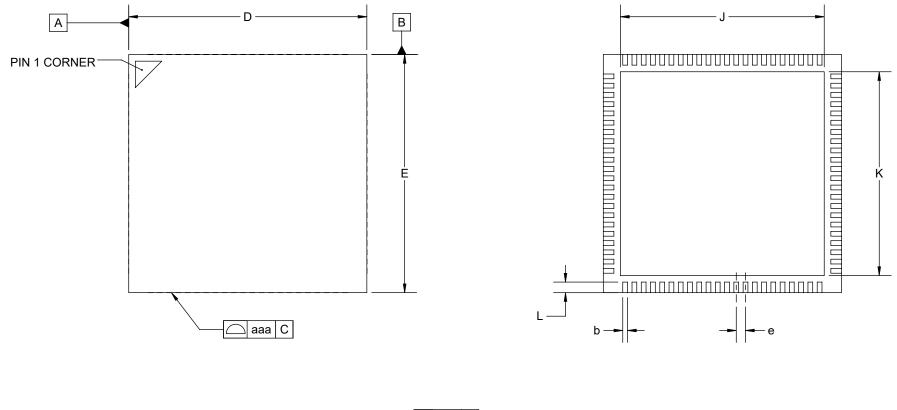
Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams.

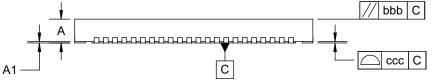
Tolerances: Hole diameters ±0.0254mm [±0.001"], Pitches (from true position) ±0.0762mm [±0.003"], substrate thickness tolerance ±10%, all other tolerances ±0.127mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

SG25-QFN-2010 Drawing Material: N/A		STATUS: Released	SHEET: 1 OF 4	REV. A	
	Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodelectronics.com	Finish: N/A Weight: 10.06	ENG: M. Newby	DRAWN BY: M. Raske	SCALE: 3:1
			FILE: SG25-QFN-2010 Dwg	DATE: 06/21/2018	



SG25-QFN-2010 Drawing Material: N/A		STATUS: Released	SHEET: 2 OF 4	REV. A
Ironwood Electronics, Inc. Tele: (800) 404-0204	Finish: N/A Weight: 10.06	ENG: M. Newby	DRAWN BY: M. Raske	SCALE: 6:1
www.ironwoodelectronics.com		FILE: SG25-QFN-2010 Dwg	DATE: 06/21/2018	





Dimensions are in millimeters.

- 1.
- Interpret dimensions and tolerances per ASME Y14.5M-1994. Dimension b is measured at the maximum solder ball diameter, parallel to datum plane C. Datum C (seating plane) is defined by the spherical crowns of the solder balls. Parallelism measurement shall exclude any effect of mark on top surface of package. 2.
- 3.
- 4.

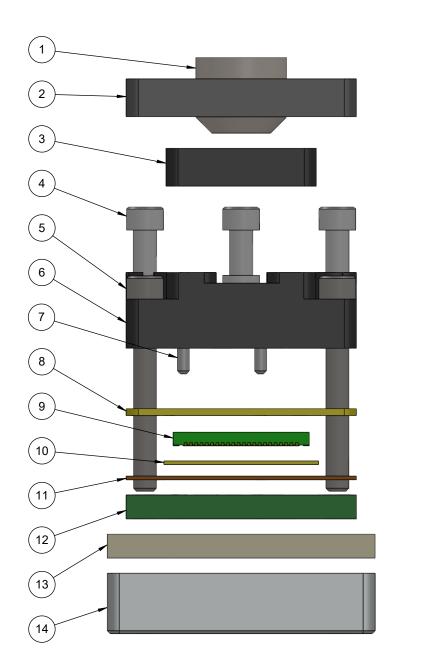
Description: Compatible Device

Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams.

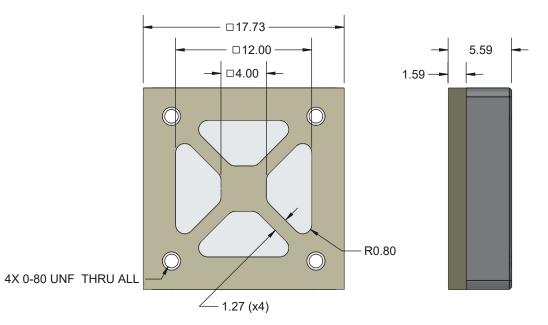
Tolerances: Hole diameters ±0.03mm [±0.001"], Pitches (from true position) ±0.025mm [±0.001"], substrate thickness tolerance ±10%, all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

SG25-QFN-2010 Drawing			STATUS: Released SHEET: 3 OF 4	SHEET: 3 OF 4	REV. A
€	Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodelectronics.com	Finish: N/A Weight: 10.06	ENG: M. Newby	DRAWN BY: M. Raske	SCALE: 7:1
			FILE: SG25-QFN-2010 Dwg	DATE: 06/21/2018	

DIM	MIN	MAX	
Α	0.5	2.0	
A1	0	0.2	
b	0.13	0.23	
D	9.00 BSC		
E	9.00 BSC		
е	0.35 BSC		
J	7.6	7.8	
K	7.6	7.8	
L	0.35	0.45	
aaa	0.1		
bbb	0.1		
ccc	0.8		
eee	0.1		



ITEM NO.	DESCRIPTION	Material
1	Compression Screw M6x1 Stainless Steel	
2	Socket Lid	7075-T6 Aluminum Alloy
3	Compression Plate	7075-T6 Aluminum Alloy
4	#0-80 Shoulder Screw	Stainless Steel
5	#0-80 x 0.5 Socket Head Cap Screw	Alloy Steel
6	Socket Base	7075-T6 Aluminum Alloy
7	Alignment Pin 1/32" dia. x 1/8" Ing	Stainless Steel
8	IC Guide	High Temp Plastic
9	Test Chip, QFN88	N / A
10	Conductive Angled Elastomer	Gold Plated Brass Filaments in Silicon
11	Elastomer Guide	High Temp Plastic
12	Test PCB, QFN88	N / A
13	Insulation Plate	FR4 / FR5
14	Backing Plate	7075-T6 Alumium Alloy



Description: Socket, Backing Plate Detail

Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams. <u>Tolerances</u>: Hole diameters ±0.03mm [±0.001"], Pitches (from true position) ±0.025mm [±0.001"], substrate thickness tolerance ±10%, all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

BACKING & INSULATION PLATE DETAIL 3:1 SCALE

SG25-QFN-2	010 Drawing	Finish: N/A	STATUS: Released	SHEET: 4 OF 4	REV. A
	Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodelectronics.com		ENG: M. Newby	DRAWN BY: M. Raske	SCALE: 4:1
			FILE: SG25-QFN-2010 Dwg	DATE: 06/21/2018	